

REMARKS/ARGUMENTS

This case has been carefully reviewed and analyzed, and reconsideration and favorable action is respectfully requested.

CLAIM REJECTION UNDER 35 U.S.C. 102(b)

5 Claims 1, 9, 11, 12 and 15 were originally rejected under 35 U.S.C. 102(b) as being anticipated by Hajicek et al.

CLAIM REJECTION UNDER 35 U.S.C. 103(a)

 Claims 2-6, 10 and 16-20 were originally rejected under 35 U.S.C. 103(a) as being unpatentable over Hajicek et al. In addition, claims 7, 8, 13 and 14 were
10 originally rejected under 35 U.S.C. 103(a) as being unpatentable over Hajicek et al. in view of Smith et al.

 Responsive to this, claim 1 is amended to make the claimed invention more distinguishably patentable over the prior arts cited by the Examiner. In addition, claim 12 is deleted and claim 11 is amended which is substantially the combination
15 of original claims 11 and 12 to make the claimed invention more distinguishably patentable over the prior arts cited by the Examiner. Applicant also submits the following comments.

 The claimed invention discloses “a heat dissipation method for an electronic apparatus comprising a housing, and a circuit board mounted in the
20 housing, the heat dissipation method comprising the steps of: step 1: providing a heatsink plate having a bottom face rested on a surface of the housing; step 2:

providing a heat conductive plate having a bottom face rested on a top face of the heatsink plate and a top face rested on a bottom face of the circuit board; step 3: transmitting heat produced by the circuit board to the heatsink plate which is connected to the housing; step 4: carrying the heat away from the housing” as
5 disclosed in the amended claim 1.

The claimed invention also discloses “an electronic apparatus comprising: a housing; a circuit board mounted in the housing; and a heatsink device mounted between and rested on the housing and the circuit board; wherein the heatsink device includes a heatsink plate having a bottom face rested on a surface of the housing, and
10 a heat conductive plate having a bottom face rested on a top face of the heatsink plate and a top face rested on a bottom face of the circuit board; wherein the heatsink device is used to dissipate heat produced by the circuit board; wherein the heat produced by the circuit board is transmitted to the heatsink plate which is connected to the housing, and is carried away from the housing” as disclosed in the amended
15 claim 11.

With reference to the Hajicek reference, it disclosed a circuit assembly 10 including a printed circuit board 12, two heat generating electronic components 18 and 20 surface mounted on the printed circuit board 12, a heat conducting metal plate 22 mounted on the printed circuit board 12, a heat conducting pad 24 mounted on the
20 heat conducting metal plate 22, and a heat sink member 26 mounted on the heat

conducting pad 24. The circuit assembly 10 is enclosed within a housing 44 which includes housing parts 46 and 48.

In comparison, in the Hajicek reference, the heat is conducted away from the heat generating electronic components 18 and 20 to the heat sink member 26, so that the circuit assembly 10 is used to transmit the heat produced by the heat generating electronic components 18 and 20 on the printed circuit board 12 to the heat sink member 26 on the printed circuit board 12. Therefore, the circuit assembly 10 is used to dissipate the heat produced by the heat generating electronic components 18 and 20 instead of the printed circuit board 12.

On the contrary, in the claimed invention, the heatsink device is used to dissipate heat produced by the circuit board, and the heat produced by the circuit board is transmitted to the heatsink plate which is connected to the housing, and is carried away from the housing.

Thus, the Hajicek reference does not teach “the heatsink device is used to dissipate heat produced by the circuit board, and the heat produced by the circuit board is transmitted to the heatsink plate which is connected to the housing, and is carried away from the housing” as disclosed in the amended claim 11 of the claimed invention and does not teach “transmitting heat produced by the circuit board to the heatsink plate which is connected to the housing, and carrying the heat away from the housing” as disclosed in the amended claim 1 of the claimed invention.

Accordingly, from the above mentioned descriptions, it is apparent that the amended claim 1 and 11 have disclosed a container whose construction and function are quite different from and patentably distinguishable over the Hajicek reference. It is believed that the Hajicek reference, whether taken alone or in combination with the Smith reference does not render obvious the claimed invention. Therefore, it is believed that, the rejections under 35 U.S.C. 102(b) and 103(a) should be withdrawn, and the claims 1-11 and 13-20 should be allowable.

In view of the foregoing amendments and remarks, Applicant submits that the application is now in a condition for allowance and such action is respectfully requested. If any points remain in issue, which the Examiner feels could best be resolved by either a personal or a telephone interview, he is urged to contact Applicant's attorney at the exchange listed below.

This Amendment was prepared by Applicant, and is being submitted without substantive change by the undersigned Attorney.

Respectfully submitted,



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